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PATENT

10/29/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Paul A. Farrar
Appl. No. : 09/909,181
Filed : July 19, 2001
For : A METHOD OF USING
FOAMED INSULATORS IN
THREE DIMENSIONAL
MULTICHIP STRUCTURES
Examiner : Chris C. Chu

) Group Art Unit 2815 *Am H*
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I hereby certify that this correspondence and all
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Patent and Trademark Office, P.O. Box 2327,
Arlington, VA 22202, on
October 7, 2002
(Date)
Linda H. Liu, Reg. No. 51,240

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AMENDMENT

United States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed July 5, 2002, please amend the above captioned application as follows:

IN THE DRAWINGS:

Please amend the drawings to conform to the drawings provided by the SUBMISSION OF PROPOSED DRAWING AMENDMENT FOR APPROVAL BY EXAMINER documented submitted concurrently herewith.

IN THE CLAIMSPlease amend the claims as follows:

1. (Amended) A high density semiconductor structure having a plurality of integrated circuit chips, comprising:
a first integrated circuit chip having an upper bonding surface;